XPedite7330

The XPedite7330 is a 3U, conduction- or air-cooled, CompactPCI (cPCI), single board computer based on the Intel® Core™ i7 processor and Intel® QM57 chipset. With dual cores operating at 2.53, 2.0, 1.06, or 1.33 GHz, the Intel® Core™ i7 delivers enhanced performance and efficiency for today’s network information processing and other embedded computing applications.

Complementing processor performance, the XPedite7330 features up to 4 GB of DDR3-1066 ECC SDRAM in two channels, 32 MB of NOR boot flash, up to 16 GB of NAND flash, configurable as system controller or peripheral, hosts a PrPMC or XMC, two 10/100/1000BASE-T Ethernet ports out J2, two RS-232/422/485 serial ports out J2, Wind River VxWorks BSP, Linux BSP, Microsoft Windows drivers, GHS INTEGRITY BSP (contact factory), QNX Neutrino BSP (contact factory), LynuxWorks LynxOS BSP (contact factory), Wind River VxWorks BSP, Linux BSP, Microsoft Windows drivers, GHS INTEGRITY BSP (contact factory), QNX Neutrino BSP (contact factory), LynuxWorks LynxOS BSP (contact factory).
Processor
- Intel® Core™ i7 processor operating at 2.53, 2.0, 1.06, or 1.33 GHz
- Dual-core with hyper-threading technology
- Intel® QM57 chipset
- Dual-channel integrated memory controller
- Integrated graphics controller
- 4 MB of shared cache

Memory
- Up to 4 GB of DDR3-1066 ECC SDRAM in two channels
- 32 MB of NOR boot flash
- Up to 16 GB of NAND flash

J1 cPCI Interface
- 32-bit PCI interface operating at 33 or 66 MHz
- System controller-capable with onboard clocking and arbitration
- Peripheral slot-capable

J2 cPCI Interface
- Two 10/100/1000Base-T Ethernet ports
- Two RS-232/422/485 serial ports
- Four GPIO signals
- Four SATA ports
- Two USB 2.0 ports
- One DVI port

PrPMC/XMC Site
- 32-bit, 33 MHz PCI bus (PMC interface)
- x8 PCIe port (XMC interface)

Software Support
- Wind River VxWorks BSP
- Linux BSP
- Microsoft Windows drivers
- GHS INTEGRITY BSP (contact factory)
- QNX Neutrino BSP (contact factory)
- LynxWorks LynxOS BSP (contact factory)

Physical Characteristics
- 3U conduction- or air-cooled CompactPCI form factor
- Dimensions: 100 mm x 160 mm

Environmental Requirements
Contact factory for appropriate board configuration based on environmental requirements.
- Supported ruggedization levels (see chart below): 1, 3, 5
- Conformal coating available as an ordering option

Power Requirements
- Power will vary based on CPU frequency and application. Please consult factory.

<table>
<thead>
<tr>
<th>Supported Ruggedization Level</th>
<th>Level 1</th>
<th>Level 3</th>
<th>Level 5</th>
</tr>
</thead>
<tbody>
<tr>
<td>Cooling Method</td>
<td>Standard Air-Cooled</td>
<td>Rugged Air-Cooled</td>
<td>Conduction-Cooled</td>
</tr>
<tr>
<td>Operating Temperature</td>
<td>0 to +55°C ambient (300 LFM)</td>
<td>-40 to +70°C (600 LFM)</td>
<td>-40 to +85°C (board rail surface)</td>
</tr>
<tr>
<td>Storage Temperature</td>
<td>-40 to +85°C ambient</td>
<td>-55 to +105°C ambient</td>
<td>-55 to +105°C ambient</td>
</tr>
<tr>
<td>Vibration</td>
<td>0.002 g²/Hz, 5 to 2000 Hz</td>
<td>0.04 g²/Hz (maximum), 5 to 2000 Hz</td>
<td>0.1 g²/Hz (maximum), 5 to 2000 Hz</td>
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<tr>
<td>Shock</td>
<td>20 g, 11 ms sawtooth</td>
<td>30 g, 11 ms sawtooth</td>
<td>40 g, 11 ms sawtooth</td>
</tr>
<tr>
<td>Humidity</td>
<td>0% to 95% non-condensing</td>
<td>0% to 95% non-condensing</td>
<td>0% to 95% non-condensing</td>
</tr>
</tbody>
</table>